

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

1-10. (canceled)

11. (original) A shielded cable comprising:

a cable body comprising electrical conductors disposed within an insulating substrate;

a vacuum metallized shielding layer disposed over the insulating substrate, and a metallized thermoform connector coupled to an end portion of the cable body and electrically coupled to the vacuum metallized layer, wherein the connector can be electrically coupled to a grounded housing so as to ground the shielding layer and connector.

12. (original) The cable of claim 11 further comprising an insulating top coating disposed over the vacuum metallized layer to insulate the vacuum metallized layer.

13. (original) The cable of claim 12 wherein the insulating top layer extends to a point short of the connector such that the connector is electrically coupled to the metallized layer.

14. (original) The cable of claim 11 wherein the vacuum metallized layer has a thickness between approximately one-half micron to twelve microns.

15. (original) The cable of claim 11 wherein the metallized thermoform is coupled to an outsize surface of a nonconductive connector.

16. (original) The cable of claim 11 wherein the connector further comprises spaced protrusions, wherein the connector is electrically coupled to the metallized layer with the spaced protrusions.

17. (currently amended) The cable of claim 16 A shielded cable comprising: a cable body comprising electrical conductors disposed within an insulating substrate;
a vacuum metallized shielding layer disposed over the insulating substrate;
a metallized thermoform connector coupled to an end portion of the cable body
and electrically coupled to the vacuum metallized layer, wherein the connector can be
electrically coupled to a grounded housing so as to ground the shielding layer and connector; and
wherein the connector further comprises spaced protrusions, wherein the
connector is electrically coupled to the metallized layer with the spaced protrusions, and
wherein the spaced protrusions have a height and spacing between an adjacent
protrusion that is no larger than one-half a wavelength of a released radiation.

18. (withdrawn) A method of shielding a cable from EMI and RFI radiation, the method comprising:

providing conductive leads disposed within a dielectric;
thermally vaporizing a metallized layer around the dielectric; and
grounding the metallized layer to a grounded housing.

19. (withdrawn) The method of claim 18 wherein grounding comprises electrically coupling the metallized layer to the grounded housing with a metallized thermoform connection assembly.

20. (withdrawn) The method of claim 18 wherein thermally vaporizing comprises maintaining the temperature of the dielectric below approximately 150°F.

21. (withdrawn) The method of claim 18 wherein thermal vaporizing comprises creating a substantial uniform metallized layer on the dielectric.

22. (withdrawn) A shielded cable comprising:
a conductive lead encapsulated within a dielectric;
a polymer layer surrounding the dielectric;

a metallized layer surrounding the polymer layer; and
a insulative coating disposed around the metallized layer.

23. (withdrawn) The shielded cable of claim 22 wherein the metallized layer is thermally evaporated over the polymer layer so as to create a substantially uniform thickness.

24. (withdrawn) The shielded cable of claim 22 further comprising a base coating disposed between the metallized layer and the polymer layer, wherein the base coating improves adherence of the metallized layer to the polymer layer.

25. (withdrawn) The shielded cable of claim 22 wherein the polymer layer comprises a thermoformable material.

26. (withdrawn) The shielded cable of claim 22 further comprising an electrically conductive connector that is electrically coupled to the metallized layer, wherein the connector can be coupled to ground.

27. (withdrawn) The shielded cable of claim 27 wherein the electrically conductive connector comprises a metallized thermoform.

28. (withdrawn) The shielded cable of claim 27 wherein the metallized thermoform comprises a first body and a second body.

29. (withdrawn) A method of shielding a cable, the method comprising:
providing a conductive lead disposed within a dielectric;
encapsulating the dielectric with a polymer coating;
coupling a metallized layer around the polymer coating; and
insulating the metallized layer.

30. (withdrawn) The method of claim 29 wherein coupling comprises applying a base coating to the polymer to increase adhesion of the metallized layer.

31. (withdrawn) The method of claim 29 wherein coupling comprises thermally vaporizing the metallized layer onto the dielectric.

32. (withdrawn) The method of claim 29 further comprising grounding the metallized layer to a ground with a metallized thermoform.

33. (withdrawn) A cable shield for shielding a cable body, the shield comprising:

a thermoform body comprising an inner surface and outer surface, the thermoform body sized and shaped to surround the cable; and

a metal layer disposed along one of the inner surface and outer surface.

34. (withdrawn) The cable shield of claim 33 further wherein the thermoform body comprises a first body and a second body.

35. (withdrawn) The cable shield of claim 34 wherein the first body and second body are coupled together with a clamp.

36. (withdrawn) The cable shield of claim 33 wherein the thermoform body comprises at least one of ribs, cutouts, and corrugation to facilitate flexing of the thermoform body.

37. (withdrawn) The cable shield of claim 33 wherein the metallized layer is disposed along the outer surface of the thermoform body, the shield further comprising an insulating layer disposed over the metal layer.

38. (withdrawn) The cable shield of claim 33 wherein the metallized thermoform comprises an integral connector at an end of the thermoform body, wherein the integral connector can shield a connector pin assembly of the cable.

39. (withdrawn) A method of shielding a cable, the method comprising: providing a cable body having a body and at least one connector pin assembly;

placing a metallized thermoform around the cable body and connector pin assembly;

grounding the metallized thermoform.

40. (withdrawn) The method of claim 39 wherein placing comprises snap fitting the metallized thermoform around the cable body.

41. (new) The cable of claim 17 further comprising an insulating top coating disposed over the vacuum metallized layer to insulate the vacuum metallized layer.

42. (new) The cable of claim 41 wherein the insulating top layer extends to a point short of the connector such that the connector is electrically coupled to the metallized layer.

43. (new) The cable of claim 17 wherein the vacuum metallized layer has a thickness between approximately one-half micron to twelve microns.

44. (new) The cable of claim 17 wherein the metallized thermoform is coupled to an outsize surface of a nonconductive connector.